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U.S. PTO
12/010018
01/18/2008

103478285

Docket No.: 069576-0332

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Byoung Hwa LEE, Sung Kwon WI, Hae Suk CHUNG, Dong
Seok PARK, Sang Soo PARK, Min Cheol PARKAdditional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): December 11, 2007

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: SAMSUNG ELECTRO-MECHANICS CO.,
LTD.

Internal Address:

Address: 314 Maetan3-dong, Yeongtong-gu, Suwon,
Gyeonggi-do, REPUBLIC OF KOREAAdditional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No(s).

☒ This document is being filed together with a new application

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

Phone Number: 202.756.8000

Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

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9. Signature.

Stephen A. Becker, 26,527

Signature

Date

Name and Registration No. of Person Signing

Total number of pages including cover sheet, attachments and documents: 3

PATENT
REEL: 020441 FRAME: 0664

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>LEE, Byoung Hwa</u>	(5) <u>PARK, Sang Soo</u>
(2) <u>WI, Sung Kwon</u>	(6) <u>PARK, Min Cheol</u>
(3) <u>CHUNG, Hae Suk</u>	(7) _____
(4) <u>PARK, Dong Seok</u>	(8) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto
SAMSUNG ELECTRO-MECHANICS CO., LTD.

314 Maetan3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States America as defined in 35 U.S.C. 100 in the invention entitled

MULTILAYER CHIP CAPACITOR

(a) for which an application for United States Letters Patent was filed on _____
and identified by United States Serial No. _____; or

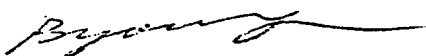
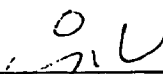
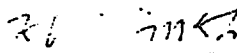

(b) for which an application for United States Letters Patent was executed _____
and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissue substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successor assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

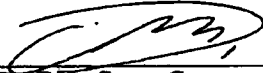
DATE SIGNED

1) <u></u>	<u>2007. 12. 11</u>
Name: LEE, Byoung Hwa	
2) <u></u>	<u>2007. 12. 11</u>
Name: WI, Sung Kwon	
3) <u></u>	<u>2007. 12. 11</u>
Name: CHUNG, Hae Suk	
4) <u></u>	<u>2007. 12. 11</u>
Name: PARK, Dong Seok	

PATENT

REEL: 020441 FRAME: 0665

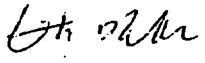
5)



Name: PARK, Sang Soo

2007. 12. 11

6)



Name: PARK, Min Cheol

2007. 12. 11